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Chairman ETSI TC SCP

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3GPP TSG CT WG6
3GPP TSG SA WG3
EMVCo
European Payment Council
GlobalPlatform
GSMA
OMA SpecWorks
oneM2M
SIMalliance

Re: TS 103 465 Smart Secure Platform (SSP); Requirements Specification (Release 15)

Good day

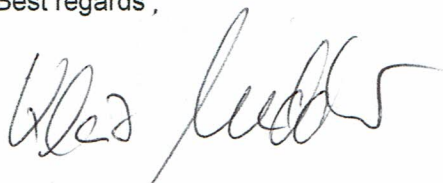
Following the liaison statement from our meeting in Brussels in March of this year it is my privilege and pleasure to provide you today with the first version of the requirement specification for the Smart Secure Platform (SSP) which was published by ETSI earlier this week.

The objective behind the development of this next generation platform was to provide an open, flexible and cost efficient secure platform suitable for multiple applications in various industry sectors. It gives the issuer the choice of several physical interfaces and form factors, including SPI, I2C, embedded, and integrated into a System on Chip (SoC). A new flexible file system and capabilities to support various authentication methods are amongst the offerings while still supporting features defined for a UICC such as Toolkit and the contactless interface to allow a smooth transition of applications. SSP is a highly scalable, thus cost efficient solution optimized to fit many requirements.

Please let me know if this new platform finds your interest and you would like a closer look at the further development of this specification as well as of those defining the technical realisation. Just drop me an email (klaus.vedder (at) Samsung.com) and I will provide you with a personal invitation to attend some of our meetings.

In any case, we will keep you informed about the advancement of the Smart Secure Platform for all industry sectors.

Best regards ,



Next meetings:

SCP REQ #77	17-19 June 2019	Seoul, Korea
SCP #88	20-21 June 2019	Seoul, Korea
SCP TEC #81	08-12 July 2019	San Diego, CA, USA